

REMARKS

Reconsideration and allowance of this application are respectfully requested in light of the above amendments and the following remarks.

The Applicants wish to thank the examiners for the courtesy shown to their representatives during a personal interview on July 10, 2003.

During the interview, it was agreed that claims 1, 2, 4, and 5-30 would be allowable over the prior art of record if claim 4 were amended to include the subject matter of claim 17, if claim 16 were amended as set forth above, and if claims 3 and 17 were canceled.

It was also agreed that the subject matter of new claims 31 and 32 distinguish over the prior art of record and specifically over the Kanji (JP'854) and Morihiro (JP'946) combination.

These amendments have been made, so that the above-noted claims are now deemed to be in condition for allowance. Also, claim 12, which depended from canceled claim 3, has also been canceled.

New claims 33-36 depend from claim 31 and thus are also deemed to be allowable over the prior art of record.

A new Fig. 1A and a proposed revision of Fig. 4(c) are submitted herewith for approval.

New Fig. 1A is provided to illustrate the resin contacting the bottom of the chip. Fig. 4(c) is amended to show proper cross-hatching.

Fig. 2 and the description at specification page 16, line 22 et seq. provide support for new Fig. 1A which shows the chip 12 wider than die pad portion 11, with the resin 15 thus contacting the bottom of the chip. Specification page 22, lines 1-2 describes contact through adhesiveness between the resin and the rear face of chip 12.

A courtesy copy of the Information Disclosure Statement of August 28, 2001 is attached, as requested by the examiners during the interview.

During the interview, it was noted that in JP'946, the inner lead is unsealed at the bottom surface and wraps around the resin block; thus, it does not have the problem of the lead tending to pull away from the resin block. Therefore, it was discussed that there is no motivation to incorporate into the JP'946 device the arrangement of the inner lead portions of JP'042 submitted in the IDS of August 24, 2001, since the inner lead portions of JP'042 are provided to prevent the leads from being removed from the resin block.

Also, there is no motivation to incorporate into the JP'946 device the arrangement of the inner lead portions of JP'042 for

further reasons. In JP'042, sealing resin leaves the entire outer lead portions unsealed, so it has a problem that the outer lead portions tend to pull away from the resin block. But in JP'946 Fig. 1(b), sealing resin seals an upper region of the outer lead portions. Thus, JP'946 Fig. 1(b) does not have the problem of the outer lead portions tending to pull away from the resin block.

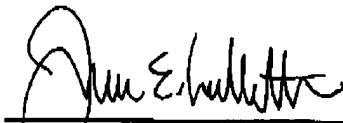
Even if JP'851 and JP'042 were combined, the claimed invention achieves unexpected results thereover (see MPEP 716.02(a)). The claimed invention results in the groove portions absorbing a stress acting on the inner lead portions even if the inner lead portions have a single-side molding structure. This stress acting on the inner lead portions occurs only if the inner lead portions have a single-side molding structure. JP'946 and JP'042 do not provide for groove portions that absorb stress acting on the inner lead portions even if the inner lead portions have a single-side molding structure. Therefore, the claimed invention has unexpected results.

For at least the above reasons, it is respectfully submitted that all present claims are directed to allowable subject matter. A Notice of Allowance is respectfully solicited.

If any issues remain which may best be resolved through a telephone communication, the examiner is requested to telephone the

undersigned at the local Washington, D.C. telephone number listed below.

Respectfully submitted,



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